

Molded Inductor 3.3µH



APPLICATIONS

- Battery-powered devices
- Portable devices
- Embedded computing
- High-current SMPS
- High-frequency SMPS
- POL converters
- FPGA

FEATURES

- Size 3.5mmx3.2mmx1.8mm
- Molded Construction
- Low Audible Noise
- Soft Saturation
- Stable Over High Temperatures
- Max Operating Temp +125°C
- RoHS/REACH-Compliant, Halogen-Free

GENERAL SPECIFICATIONS

Parameter			Value	Unit
Inductance ⁽¹⁾	L	±20%	3.3	μH
Resistance	R _{DC}	typ	121	mΩ
Resistance MAX	R _{DC MAX}	max	146	mΩ
Rated Current ⁽²⁾	I _R	typ	2.5	Α
Saturation Current _{25°C} ⁽³⁾	ISAT 25°C	typ	3.7	Α
Saturation Current 100°C (4)	ISAT 100°C	typ	3.7	Α
Resonance Frequency	fr	typ	40	MHz

⁽¹⁾ Inductance	Measured at 100kHz, 100mA
⁽²⁾ Rated Current	Rated current will cause the coil temperature rise ΔT of 40K I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35µm Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.
(3) Saturation Current 25°C	Saturation current will cause L to drop from 30% at 25°C ambient temperature
(4) Saturation Current 100°C	Saturation current will cause L to drop from 30% at 100°C ambient temperature
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently
Operating Condition	Operating temperature: -40°C to +125°C (including temp rise)
	Should not exceed +125°C under worst-case operation conditions
Storage Condition	Tape and Reel packaging: -10°C to +40°C
	Humidity: <50% RH

All MPS parts are lead-free, halogen-free, and adhere to the RoHS directive. For MPS green status, please visit the MPS website under Quality Assurance. "MPS", the MPS logo, and "Simple, Easy Solutions" are registered trademarks of Monolithic Power Systems, Inc. or its subsidiaries.



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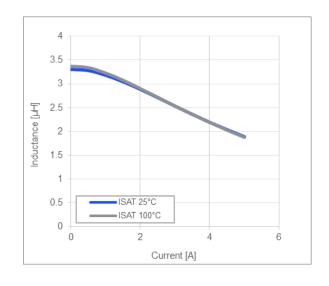
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TYPICAL PERFORMANCE CURVES



Temperature Rise vs. Current



Inductance vs. Current

Impedance vs. Frequency

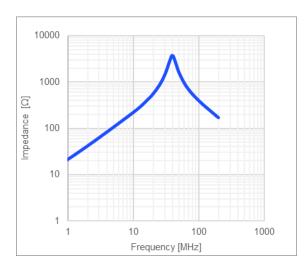
2

Current [A]

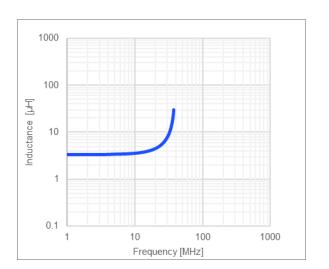
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4

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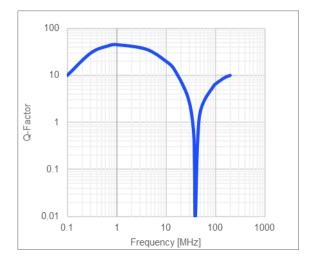
Inductance vs. Frequency

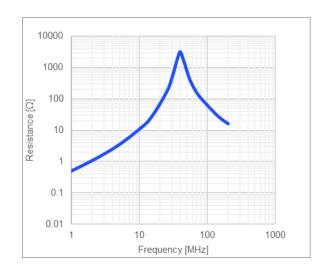




Quality Factor vs. Frequency

AC Resistance vs. Frequency

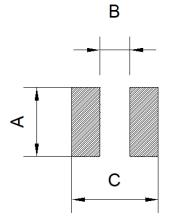






	DATTEDN	
LAND	PATTERN	

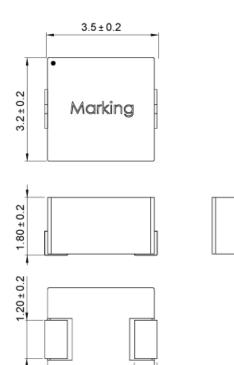
Dimensions			
А	1.45 ref.		
В	1.90 ref.		
С	4.10 ref.		
	(unit in mm)		



PRODUCT PACKAGE AND DIMENSIONS

Dimensions

(unit in mm)



 0.70 ± 0.2

TOP MARKING			
Marking			
Start of Winding	· (dot)		
Inductance Code	3.3		



ORDERING INFORMATION

Part Number	L (1)	R _D c	<i>I</i> _R ⁽²⁾	I _{SAT 25°C} ⁽³⁾	ISAT 100°C ⁽⁴⁾
	typ (µH)	typ (mΩ)	typ (A)	typ (A)	typ (A)
MPL-AY3020-R47	0.47	19.5	6.3	9	9
MPL-AY3020-R68	0.68	26	5.15	8.6	8.6
MPL-AY3020-R82	0.82	28	4.7	8	8
MPL-AY3020-1R0	1.0	30	4.3	6.2	6.2
MPL-AY3020-1R5	1.5	35	3.4	5.9	5.9
MPL-AY3020-2R2	2.2	64	3.0	5.3	5.3
MPL-AY3020-3R3	3.3	121	2.5	3.7	3.7
MPL-AY3020-4R7	4.7	173	2.0	3.1	3.1
MPL-AY3020-5R6	5.6	209	1.8	2.8	2.8
MPL-AY3020-6R8	6.8	250	1.65	2.6	2.6
MPL-AY3020-8R2	8.2	345	1.4	1.95	1.95
MPL-AY3020-100	10	370	1.3	1.75	1.75

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Operating Condition	Operating temperature: -40°C to +125°C (including temp rise)
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Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH

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